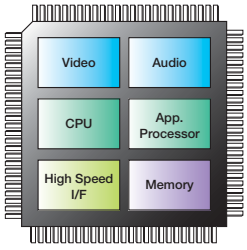
ADVANTEST

Parallel Test Solution

for Multiple Market Segments

ADVANTEST's' wide-range of optimally designed modules provides flexible test solutions that can be tailored for all SoC device types.



Digital Multimedia SoC

Module Configuration Scenario

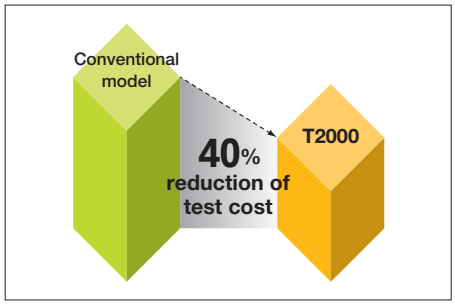
- 6.5G Digital Module
- 800M Digital Module
- AAWGD (Audio)
- BBWGD (Baseband/video)
- DPS500mA
- LCDPS

LSMF (52 slots)

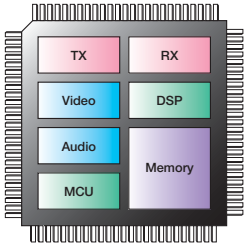
Digital Consumer Test Solution

Expandability and Flexibility

Our 52-slot LS mainframe provides the lowest test cost for the myriad of SoC devices and applications. Our modular architecture is both flexible and expandable providing customers with the lowest COT configuration for test requirement today and tomorrow.
Significant improvements in parallel test efficiency afford customers a substantial test cost savings.



Based on ADVANTEST COT model



RF + Base Band Device

Module Configuration Scenario

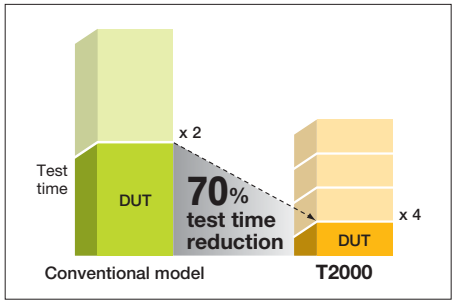
- 250MDMA
- 12GWSGA
- DPS500mA
- AAWGD
- BBWGD

GSMF (13 slots)

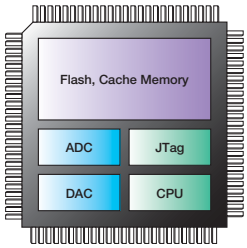
RF Test Solution

Independent quad-site RF resources (32 pin, VSG/VSA) achieve un-equalled levels of parallel test, and contribute significantly to a test cost reduction for volume production.

Realize 70% test time reduction per DUT with multi-site efficiencies greater than 85%



OPENSTAR



Microcontroller

Module Configuration Scenario
- 250MDMA
- PMU32
- DPS500mA
- 2048ch Frog Unit

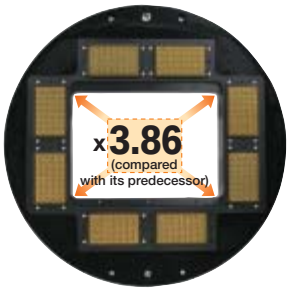
Option:
- AAWGD


LSMF (26 slots)

MCU Test Solution

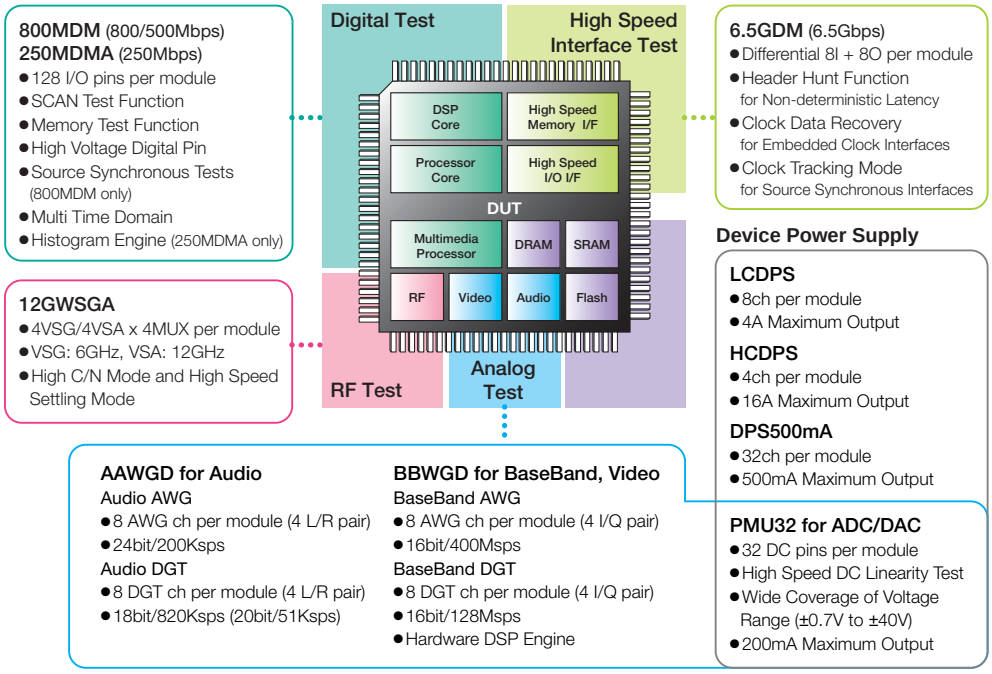
Ideal coverage and broad functionality for single-pass testing of MCU devices with both embedded AD/DA, and Flash memory in a standard T2000 configuration.
High-density channel resources and a newly developed pogo unit help customers achieve massively parallel testing of MCU wafer probe devices.

Increased area (178 x 253mm) and supporting more parallel testing



2048ch Frog unit

■ T2000-Flexible and scalable architecture addresses multiple device requirements



■ T2000 Mainframe Lineup

	SPMF	MSMF	LSMF	GSMF
# of Modules (Max)	52	52	52/26	13
MF size (WxDxH) mm	1550 x 1050 x 2000	900 x 1050 x 1900	800 x 1050 x 1600	450 x 1000 x 960
# of Site controllers (Max)	8	1	4	1
Cooling	Air/Liquid			Air

*# of modules is assumed to be only liquid-cooled modules (24mm)

ADVANTEST

http://www.advantest.co.jp

ADVANTEST CORPORATION
Shin-Marunouchi Center Building, 1-6-2 Marunouchi, Chiyoda-ku, Tokyo 100-0005, Japan Phone:+81-3-3214-7500 Fax:+81-3-3214-7705

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